



HIGH SPEED LASER FOR MICRO-HOLES & SCORING

Laser perforation is for doing micro-holes into material to allow the release of atmospheric gases from the packaging to extend the shelf life of your products (MAP) or for doing scoring, scribing in machine direction.

MOD. SM-LS

LLaser perforation for doing micro-holes into material to allow the release of atmospheric gases from the packaging to extend the shelf life of fresh products. (MAP). Our MOD. SM-LMH is typically modular and it can be mounted on just about any line The are a non-contact method of perforating. Laser focus can be adjuste for the material being processed. It's for extending shelf life of fresh products.

Features

Max material width 3000mm

Max speed 300 meters per minute

Installation on bag making machine, extruder, slitter,

printing machine and so on

Encoder to synchronize the speed Yes

Material that could be processed PE,PP and coated material

Operator language Yes
User friendly software Yes
remote assistance Yes

Touch screen Yes with predisposition 4.0















